

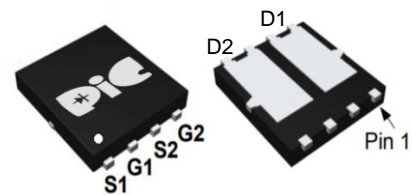
### ➤ General Description

This PAN32TV02V Dual N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent  $R_{ds(On)}$  performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

### ➤ Feature

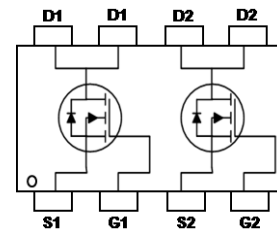
- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent  $CdV/dt$  effect decline
- Advanced high cell density Trench technology

### ➤ DFN3X3A-EP2



### ➤ Application

- DC/DC Primary Side Switch
- Industrial Synchronous
- Rectification Load Switch
- DC/DC Converters



### ➤ Absolute Maximum Ratings

| Parameter  | Symbol                  | Rating     | Units        |
|--|-------------------------|------------|--------------|
| Drain-Source Voltage                             | $V_{DS}$                | 30         | V            |
| Gate-Source Voltage                              | $V_{GS}$                | $\pm 20$   | V            |
| Continuous Drain Current, $V_{GS} @ 10V_1$       | $I_D @ T_C=25^\circ C$  | 28         | A            |
| Continuous Drain Current, $V_{GS} @ 10V_1$       | $I_D @ T_C=100^\circ C$ | 18         | A            |
| Continuous Drain Current, $V_{GS} @ 10V_1$       | $I_D @ T_A=25^\circ C$  | 7.4        | A            |
| Continuous Drain Current, $V_{GS} @ 10V_1$       | $I_D @ T_A=70^\circ C$  | 6          | A            |
| Pulsed Drain Current <sup>2</sup>                | $I_{DM}$                | 56         | A            |
| Single Pulse Avalanche Energy <sup>3</sup>       | EAS                     | 22.1       | mJ           |
| Avalanche Current                                | $I_{AS}$                | 21         | A            |
| Total Power Dissipation <sup>4</sup>             | $P_D @ T_C=25^\circ C$  | 20.8       | W            |
| Total Power Dissipation <sup>4</sup>             | $P_D @ T_A=25^\circ C$  | 1.67       | W            |
| Storage Temperature Range                        | $T_{STG}$               | -55 to 150 | $^\circ C$   |
| Operating Junction Temperature Range             | $T_J$                   | -55 to 150 | $^\circ C$   |
| Thermal Resistance Junction ambient <sup>1</sup> | R                       | 75         | $^\circ C/W$ |
| Thermal Resistance Junction-Case <sup>1</sup>    | $R_{\theta JC}$         | 6          | $^\circ C/W$ |

### ➤ Electrical Characteristics ( $T_J=25^\circ C$ Unless otherwise noted)

| Parameter                                      | Symbol                       | Conditions                                      | Min. | Typ.  | Max.      | Unit          |
|--|------------------------------|---|------|-------|-----------|---------------|
| Drain-Source Breakdown Voltage                 | $BV_{DSS}$                   | $V_{GS}=0V, I_D=250\mu A$                       | 30   | ---   | ---       | V             |
| BVDSS Temperature Coefficient                  | $\Delta BV_{DSS}/\Delta T_J$ | Reference to $25^\circ C, I_D=1mA$              | ---  | 0.022 | ---       | $V/^\circ C$  |
| Static Drain-Source On-Resistance <sup>2</sup> | $R_{DS(ON)}$                 | $V_{GS}=10V, I_D=10A$                           | ---  | ---   | 18        | m $\Omega$    |
|  |                              | $V_{GS}=4.5V, I_D=5A$                           | ---  | ---   | 30        |               |
| Gate Threshold Voltage                         | $V_{GS(th)}$                 | $V_{GS}=V_{DS}, I_D=250\mu A$                   | 1.0  | ---   | 2.5       | V             |
| $V_{GS(th)}$ Temperature Coefficient           | $\Delta V_{GS(th)}$          |   | ---  | -5.1  | ---       | $mV/^\circ C$ |
| Drain-Source Leakage Current                   | $I_{DSS}$                    | $V_{DS}=24V, V_{GS}=0V, T_J=25^\circ C$         | ---  | ---   | 1         | $\mu A$       |
|  |                              | $V_{DS}=24V, V_{GS}=0V, T_J=55^\circ C$         | ---  | ---   | 5         |               |
| Gate-Source Leakage Current                    | $I_{GSS}$                    | $V_{GS}=\pm 20V, V_{DS}=0V$                     | ---  | ---   | $\pm 100$ | nA            |
| Forward Transconductance                       | $g_{fs}$                     | $V_{DS}=5V, I_D=10A$                            | ---  | 4.5   | ---       | S             |
| Gate Resistance                                | $R_g$                        | $V_{DS}=0V, V_{GS}=0V, f=1MHz$                  | ---  | 2.5   | ---       | $\Omega$      |
| Total Gate Charge (4.5V)                       | $Q_g$                        | $V_{DS}=20V, V_{GS}=4.5V, I_D=10A$              | ---  | 7.2   | ---       | nC            |
| Gate-Source Charge                             | $Q_{gs}$                     |   | ---  | 1.4   | ---       |               |
| Gate-Drain Charge                              | $Q_{gd}$                     |   | ---  | 2.2   | ---       |               |
| Turn-On Delay Time                             | $T_{d(on)}$                  | $V_{DD}=12V, V_{GS}=10V, R_G=3.3\Omega, I_D=5A$ | ---  | 4.1   | ---       | ns            |
| Rise Time                                      | $T_r$                        |   | ---  | 9.8   | ---       |               |
| Turn-Off Delay Time                            | $T_{d(off)}$                 |   | ---  | 15.5  | ---       |               |
| Fall Time                                      | $T_f$                        |   | ---  | 6.0   | ---       |               |
| Input Capacitance                              | $C_{iss}$                    | $V_{DS}=15V, V_{GS}=0V, f=1MHz$                 | ---  | 572   | ---       | pF            |
| Output Capacitance                             | $C_{oss}$                    |   | ---  | 81    | ---       |               |
| Reverse Transfer Capacitance                   | $C_{rss}$                    |   | ---  | 65    | ---       |               |

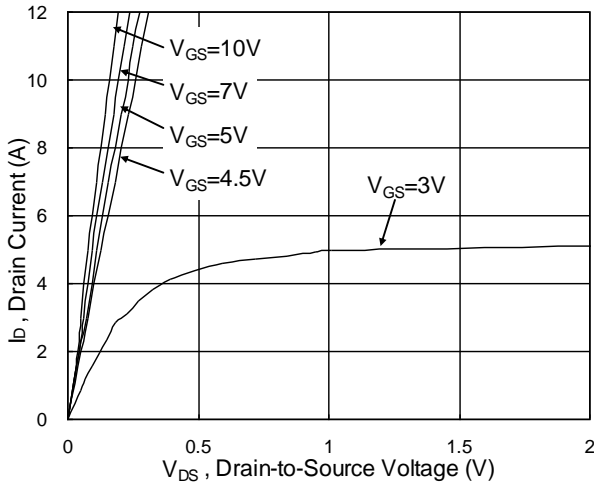
### ➤ Diode Characteristics

| Parameter                                | Symbol   | Conditions                          | Min. | Typ. | Max. | Unit |
|--|----------|-------------------------------------|------|------|------|------|
| Continuous Source Current <sup>1,5</sup> | $I_S$    | $V_G=V_D=0V, \text{Force Current}$  | ---  | ---  | 28   | A    |
| Pulsed Source Current <sup>2,5</sup>     | $I_{SM}$ |                                     | ---  | ---  | 56   | A    |
| Diode Forward Voltage <sup>2</sup>       | $V_{SD}$ | $V_{GS}=0V, I_S=1A, T_J=25^\circ C$ | ---  | ---  | 1.2  | V    |

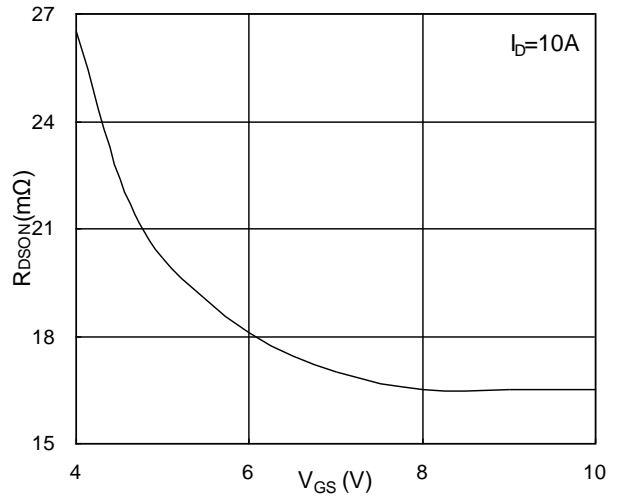
Note :

- 1.Pulse width limited by maximum junction temperature.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=21A$
- 4.Ensure that the channel temperature does not exceed  $150^\circ C$ .
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

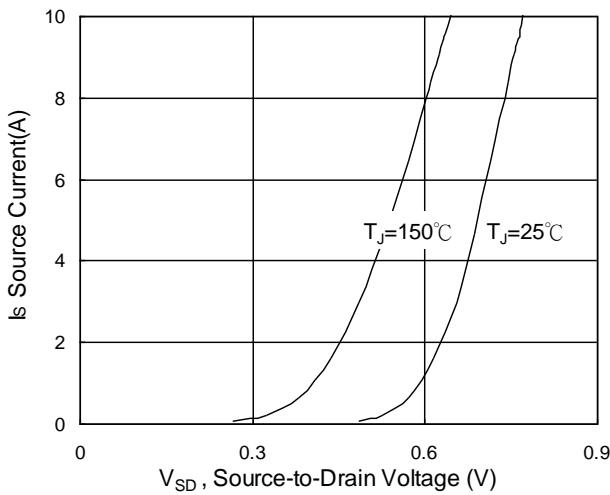
### ➤ Typical Characteristics



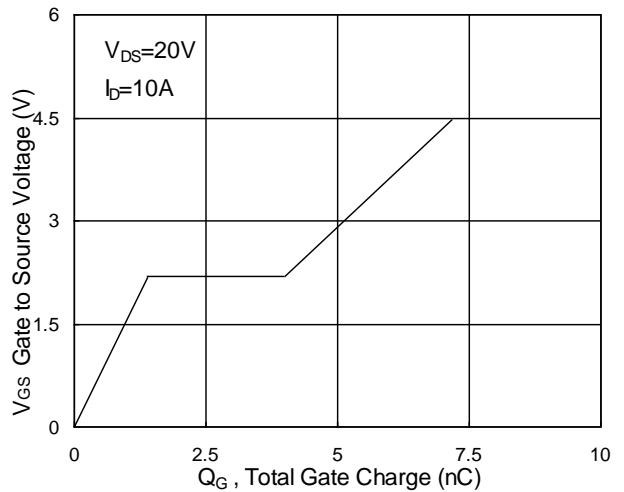
**Fig.1 Typical Output Characteristics**



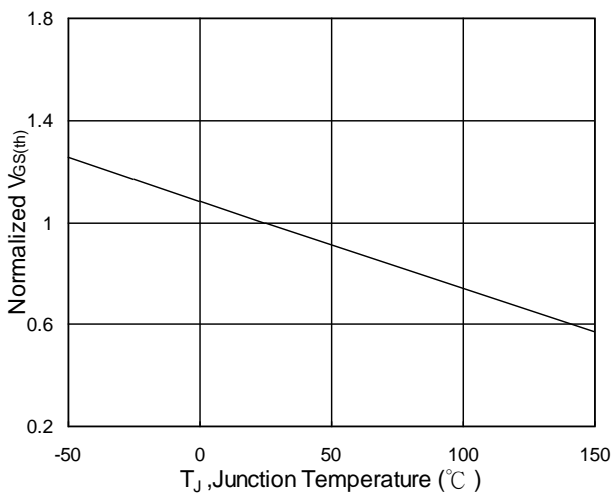
**Fig.2 On-Resistance vs. Gate-Source**



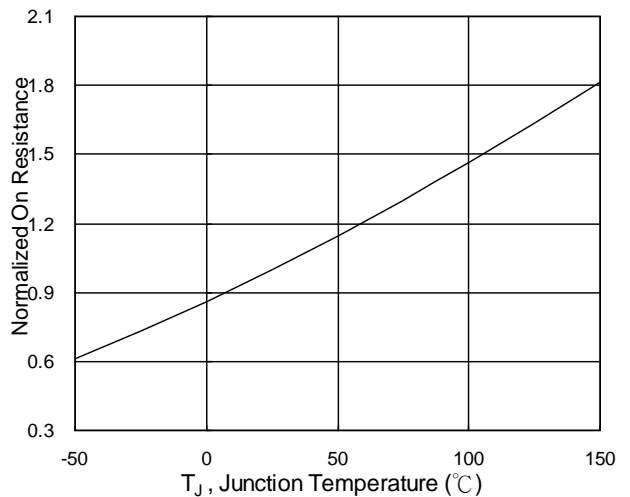
**Fig.3 Forward Characteristics Of Reverse**



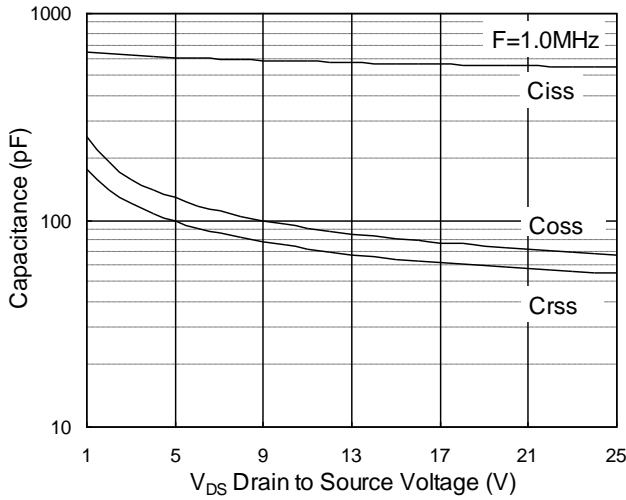
**Fig.4 Gate-Charge Characteristics**



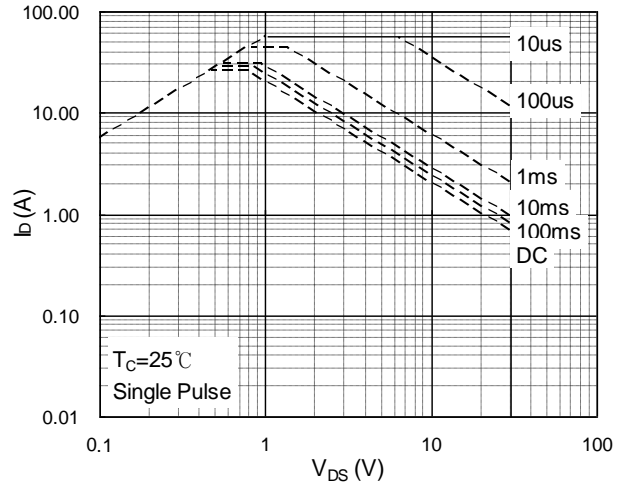
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



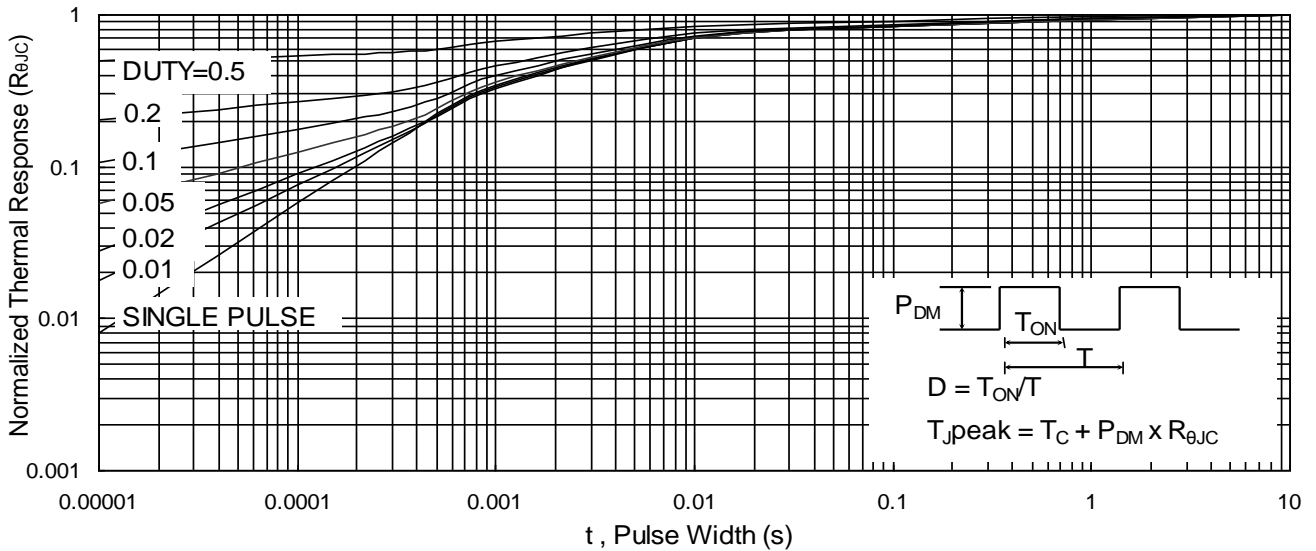
**Fig.6 Normalized  $R_{DS(ON)}$  vs.  $T_J$**



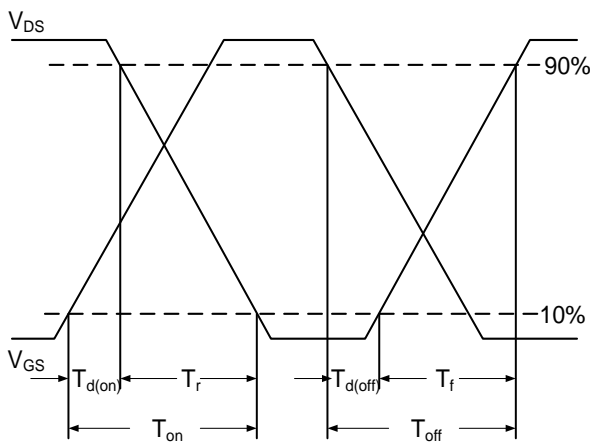
**Fig.7 Capacitance**



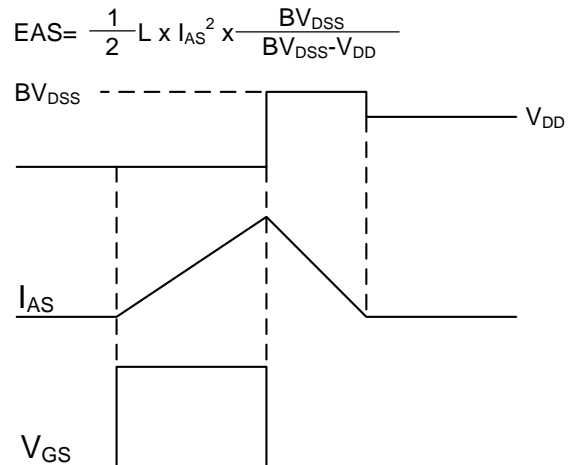
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

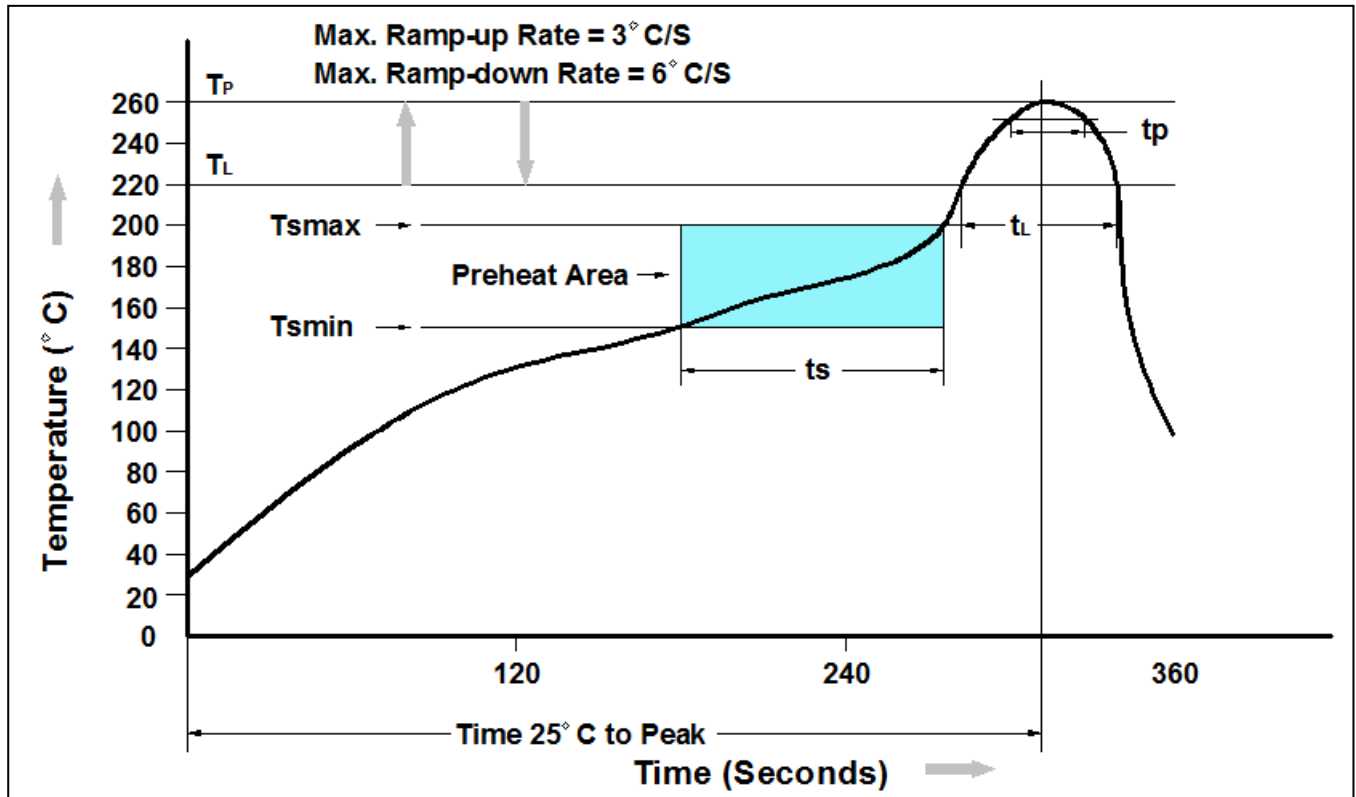


**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**

### ➤ Recommend IR Reflow Soldering Thermal Profile

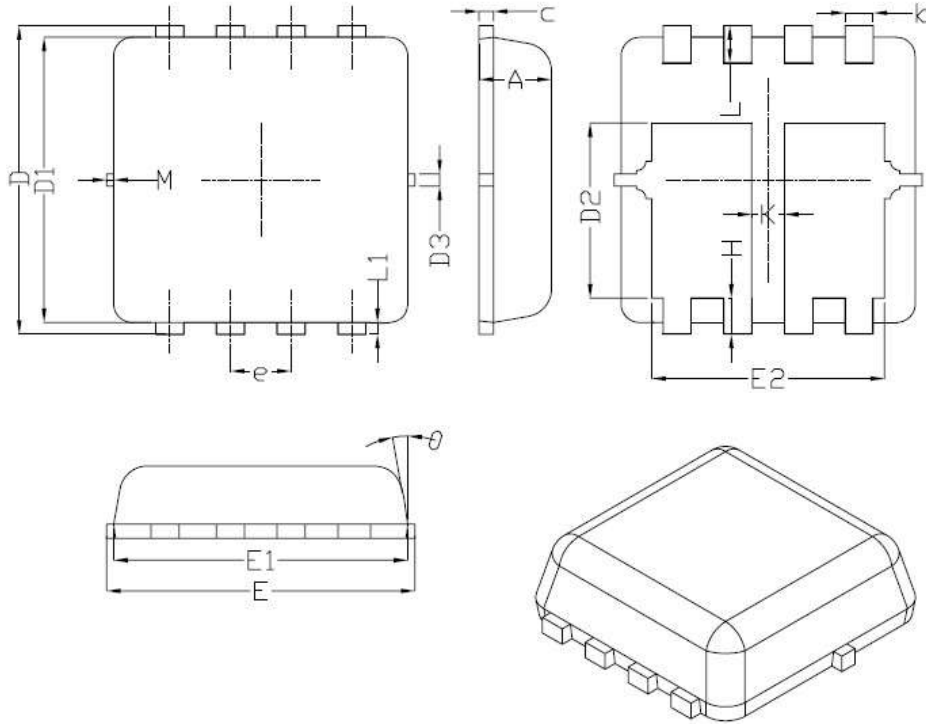


| Profile Feature   | Pb-Free Assembly Profile |
|---|--------------------------|
| Temperature Min. (T <sub>smin</sub> )                                 | 150°C                    |
| Temperature Max. (T <sub>smax</sub> )                                 | 200°C                    |
| Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> ) | 60-120 seconds           |
| Average Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )              | 3°C/second max.          |
| Liquidous Temperature (T <sub>L</sub> )                               | 217°C                    |
| Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )             | 60 – 150 seconds         |
| Peak Temperature  | 260°C +0°C / -5°C        |
| Time (t <sub>P</sub> ) within 5°C of actual Peak Temperature          | 30 seconds               |
| Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )                    | 6°C/second max           |
| Time 25°C to Peak Temperature   | 8 minutes max.           |

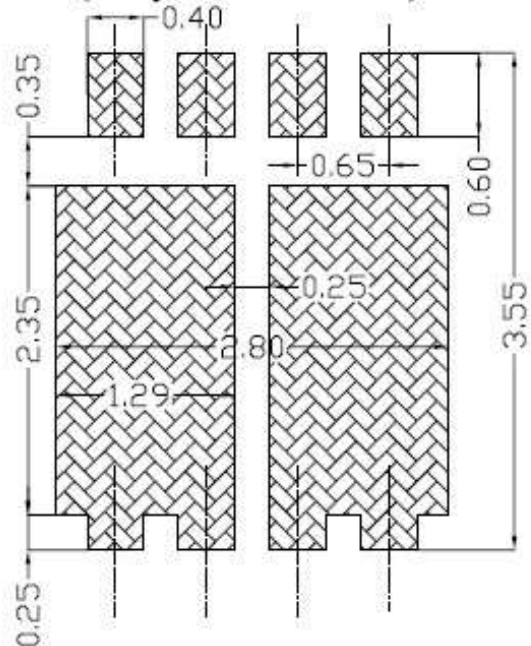
### ➤ Ordering Information

| Part Number | Description      | Quantity |
|-------------|------------------|----------|
| PAN32TV02V  | DFN3X3A-EP2 Reel | 3000 pcs |

### ➤ Package Information ( DFN3X3A-EP2 )



**Land Pattern**  
(Only for Reference)



| SYMBOL | DIMENSIONAL REQMTS |      |      |
|--------|--------------------|------|------|
|        | MIN                | NOM  | MAX  |
| A      | 0.70               | 0.75 | 0.80 |
| b      | 0.25               | 0.30 | 0.35 |
| c      | 0.10               | 0.15 | 0.25 |
| D      | 3.25               | 3.35 | 3.45 |
| D1     | 3.00               | 3.10 | 3.20 |
| D2     | 1.78               | 1.88 | 1.98 |
| D3     | —                  | 0.13 | —    |
| E      | 3.20               | 3.30 | 3.40 |
| E1     | 3.00               | 3.15 | 3.20 |
| E2     | 2.39               | 2.49 | 2.59 |
| e      | 0.65BSC            |      |      |
| H      | 0.30               | 0.39 | 0.50 |
| L      | 0.30               | 0.40 | 0.50 |
| L1     | —                  | 0.13 | —    |
| K      | 0.30               | —    | —    |
| θ      | —                  | 10°  | 12°  |
| M      | *                  | *    | 0.15 |

\* Not specified

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